PCN Number:			20200408000.1						PCN	I D	ate:	May 8, 2020	
Title: Qualify TI Ch		engdu as an additional Assembly site for select devices								es			
Cust	tom	er Contact:	PCN Manager Dept: Quality Ser										
Proposed 1 st Ship Da			te:	Aug 8,	202	20			Estimated Sam Availability:			rovided upon Request	
		Туре:				- 1							
		mbly Site				Des	<u> </u>					er Bump Site	
Assembly Process					Data Shee						er Bump Material		
		mbly Materials		-	Part numb				\mathbf{H}		er Bump Process er Fab Site		
Mechanical Specification Packing/Shipping/Labeling				Test Site							er Fab Materials		
	TUCK	ing/Shipping/L		ing	Test Process				Η		er Fab Process		
	PCN Details												
Description of Change:													
Texas Instruments is pleased to announce the qualification of TI Chengdu as additional Assembly Site for Select Devices listed in the "Product Affected" Section. Material differences are as follows.													
					TI Clark			TIO	TI Cheng				
	Mc	ount compound	1			07768			20712				
		old compound	4			08625							
	1•1				42	.08023		42	4222198				
Rea	son	for Change:											
Continuity of Supply													
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):													
None	е												
Anti	icipa	ted impact o	n Ma	terial D	ecl	laratio	n						
Material Declaration			pro rele obt	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <u>TI Eco-Info website</u> . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.									
Cha	nges	to product i	dent	ificatior	n re	esultir	i <mark>g f</mark> r	om this P	CN:				
Ass	emb	ly Site								7			
TI Clark Assembly Site Origin (22L) ASO:QAB													
TI Chengdu Assembly Site Origin (22L) ASO: CDA													
Sample product shipping label (not actual product label)													
INSTRUMENTS Image: Additional state of the state o													
Product Affected													
TPS2556DRBR TPS2556DRB					ΒT								

Qualification Report

Approve Date 06-Apr-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: <u>TPS2556DRBR</u>	QBS Product Reference: <u>TPS2556DRB</u>	QBS Package Reference: <u>BQ25895RTWR</u>	QBS Package Reference: <u>LP5922</u>	QBS Package Reference: <u>TPS3850G09DRC</u>
AC	Autoclave 121C	96 Hours	-	-	-	-	3/240/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0
HTOL	Life Test, 125C	1000/hrs @125C	-	-	-	1/80/0	-
HTSL	High Temp Storage Bake 150C	1000/hrs @150C	-	-	-	3/239/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0	-	3/231/0
LU	Latch-up	(per JESD78)	-			-	1/6/0
MQ	Manufacturability (Assembly)	(Approved by AT site)	3/Pass	1/Pass	3/Pass	3/3/0	1/Pass
тс	Temperature Cycle, -65/150C	(MSL 2 / 260C)	3/231/0	-	3/231/0	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	3/231/0	3/239/0	-

- QBS: Qual By Similarity

- Qual Device TPS2556DRBR is qualified at LEVEL2-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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